

General Description

This MOSFET uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

Features

- Low gate charge
- 100% UIS tested, 100% DVDS tested
- High power and current handling capability
- Lead free product is acquired

Applications

- Power management switches
- Portable equipment and battery powered systems



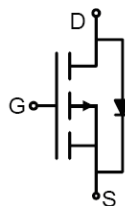
Key Performance Parameters

Parameter	Value	Unit
V_{DS}	-100	V
$R_{DS(ON), max} @ V_{GS}=10V$	108	m Ω

Marking Information

Product Name	Package	Marking
OSH10P85BF	SOP8	OSH10P85B

Package & Pin information



Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	-100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-3.6	A
Pulsed Drain Current ¹⁾	$I_{D,pulse}$	-14.4	A
Power Dissipation	P_D	3	W
Single pulsed avalanche energy ²⁾	E_{AS}	156	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^{\circ}\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-to-ambient	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$

Electrical Characteristics at $T_j=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	-100			V	$V_{GS}=0\text{ V}, I_D=-250\text{ }\mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	-1.0		-2.5	V	$V_{DS}=V_{GS}, I_D=-250\text{ }\mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		86	108	$\text{m}\Omega$	$V_{GS}=-10\text{ V}, I_D=-10\text{ A}$
Drain-source on-state resistance	$R_{DS(ON)}$		91	120	$\text{m}\Omega$	$V_{GS}=-4.5\text{ V}, I_D=-8\text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$
				-100		$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$
Drain-source leakage current	I_{DSS}			-1	μA	$V_{DS}=-100\text{ V}, V_{GS}=0\text{ V}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		3369		pF	$V_{GS}=0\text{ V}$, $V_{DS}=-50\text{ V}$, $f=1.0\text{ MHz}$
Output capacitance	C_{oss}		72.3		pF	
Reverse transfer capacitance	C_{rss}		30.4		pF	
Turn-on Delay Time	$t_{d(on)}$		11.6		ns	$V_{GS}=-10\text{ V}$, $V_{DS}=-50\text{ V}$, $R_L=5\ \Omega$, $R_{GEN}=9.1\ \Omega$
Turn-on Rise Time	t_r		17.6		ns	
Turn-Off Delay Time	$t_{d(off)}$		115.2		ns	
Turn-Off Fall Time	t_f		42		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total Gate Charge	Q_g		72		nC	$V_{GS}=-10\text{ V}$, $V_{DS}=-50\text{ V}$, $I_D=-10\text{ A}$
Gate-Source Charge	Q_{gs}		8.4		nC	
Gate-Drain Charge	Q_{gd}		17.3		nC	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Source drain current (Body Diode)	I_{SD}			-15	A	$T_A=25^\circ\text{C}$
Diode forward voltage ³⁾	V_{SD}			-1.2	V	$I_S=-10\text{ A}$, $V_{GS}=0\text{ V}$

- Note:**
- 1) Pulse width limited by maximum allowable junction temperature.
 - 2) EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=50\text{ V}$, $V_G=-10\text{ V}$, $R_g=25\ \Omega$, $L=0.5\text{ mH}$.
 - 3) Repetitive Rating: Pulse width limited by maximum junction temperature.

Electrical Characteristics Diagrams

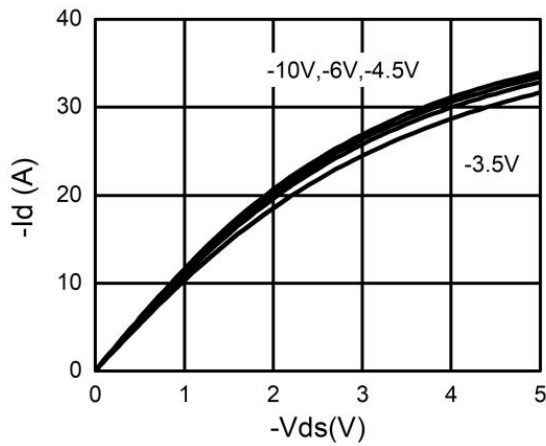


Figure 1. Typ. output characteristics

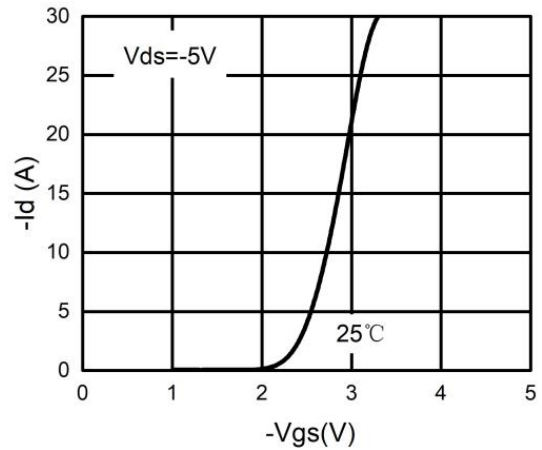


Figure 2. Typ. transfer characteristics

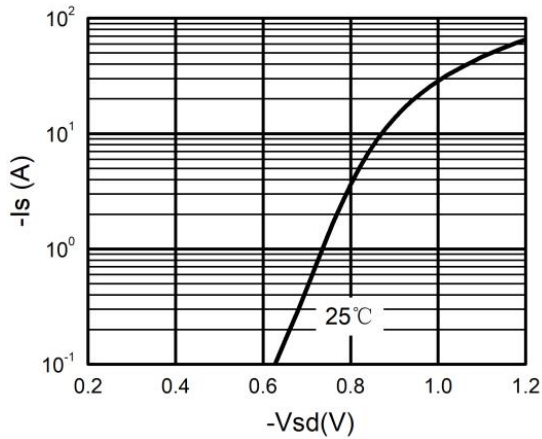


Figure 3. Body-diode characteristics

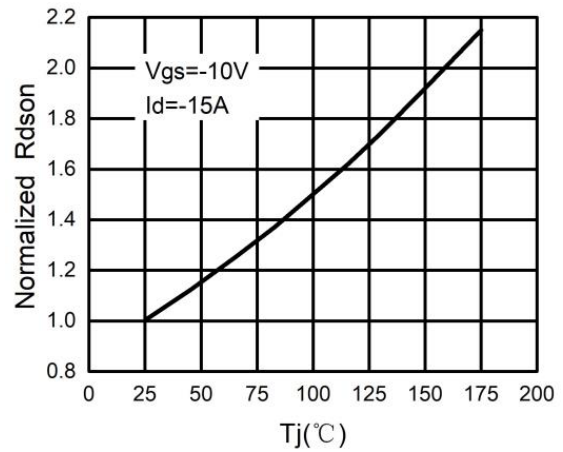


Figure 4. $R_{DS(ON)}$ vs junction temperature

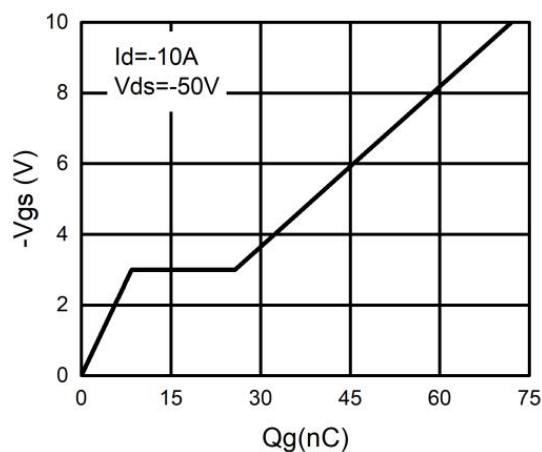


Figure 5. Gate charge waveforms

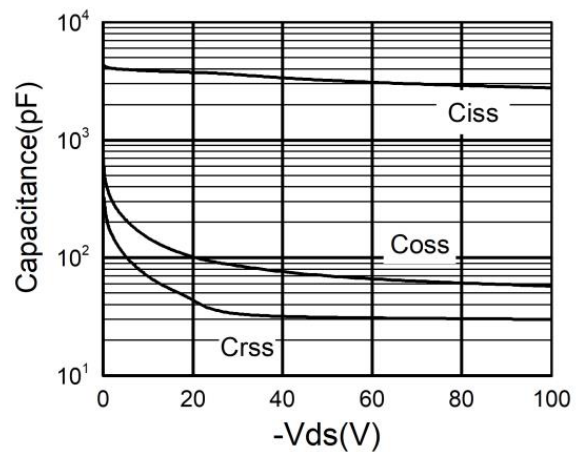


Figure 6. Capacitance

The drawing illustrates the SOP-8-G package outline with the following views and dimensions:

- Top View:** Shows the package width D , height E , and a central INDEX mark. Pin pitch is e , and pin width is b . A circular feature has a diameter of $0.25(M)$.
- Side View:** Shows pin heights A , $A2$, and $A3$. Lead angles are $\theta 3$ and $\theta 4$. A flatness tolerance of 0.10 is indicated.
- Bottom View:** Shows lead angles $\theta 1$ and $\theta 2$, and dimensions h , $R1$, R , $L2$, L , and $(L1)$.
- Cross-section B-B:** Shows the package thickness with dimensions b , $b1$, $c1$, and c . It distinguishes between the BASE METAL and the layer WITH PLATING.

Symbol	mm		
	Min.	Typ.	Max.
A	1.45	1.55	1.65
A1	0.10	0.15	0.20
A2	1.353	1.40	1.453
A3	0.55	0.60	0.65
b	0.38	-	0.51
b1	0.37	0.42	0.47
c	0.17	-	0.25
c1	0.17	0.20	0.23
D	4.85	4.90	4.95
E	5.85	6.00	6.15
E1	3.85	3.90	3.95
e	1.245	1.27	1.295
L	0.45	0.60	0.75
L1	-	1.040REF	-
L2	-	0.250BSC	-

Version1: SOP-8-G package outline dimension

Ordering Information

Package Type	Units/ Reel	Reels/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
SOP-8-G	4000	2	8000	6	48000

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